

WAFER GRINDING METHOD

ABSTRACT

A wafer grinding method for grinding, by a grindstone, a reverse side of a wafer formed on a face side thereof with devices includes a protective member forming step of covering a whole area of the face side of the wafer with a protective member, a holding step of holding the wafer by a chuck table with the protective member therebetween, and a grinding step of grinding the reverse side of the wafer by the grindstone while supplying grinding water containing a surfactant to the grindstone and the wafer.

[FIG. 1]